CLAIMS

What is claimed is:

1. A circuit apparatus, comprising:

a laminar support;

a conductive track on the laminar support;

an auxiliary conductive element electrically connected to the conductive track, wherein the auxiliary conductive element is applied by means of an apparatus for applying SMD components.

2. The apparatus of claim 1, wherein the auxiliary conductive element is electrically connected to the laminar support by means of an adhesive and soldered thereto by a wave soldering procedure.

3. The apparatus of claim 1, wherein the auxiliary conductive element is electrically connected to the laminar support by means of a cream solder and a reflow soldering procedure.

4. The apparatus of claim 1, wherein said laminar support includes a first face a second face, and a thickness, the first face exhibits a plurality of auxiliary conductive elements and a plurality of SMD electronic components, the second face

exhibits a plurality of electronic components furnished with legs, and the legs pass through the thickness of the laminar support.

5. The apparatus of claim 4, wherein the auxiliary conductive elements are mutually identical.

6. The apparatus of claim 1, wherein the auxiliary conductive element includes a metal pad.

7. The apparatus of claim 1, wherein

the auxiliary conductive element is electrically connected to the conductive track by a solder alloy; and

the auxiliary conductive element includes a metal with high electrical conductivity, and

the auxiliary conductive element is coated with a metallic layer with both high wettability and a melting temperature higher than the melting temperature of the solder alloy.

8. A flexible material strip, comprising:

a plurality of auxiliary conductive elements; and

a plurality of adjacent recesses, wherein each of the recesses houses a respective auxiliary conductive element.

9. The flexible material strip of claim 8, wherein the auxiliary conductive element includes a metal pad.

10. The flexible material strip of claim 8, wherein each auxiliary conductive element is produced from a metal with high electrical conductivity and coated with a metallic layer with both a wettability and a melting temperature sufficient for a soldering process.